

**International Gold & Silver Plate Society Stipend**

CRITERIA: Junior/Senior level, Firm commitment to a career in foodservice, Strong academic record with GPA of 3.0 or higher, Financial need and Participation in undergraduate activities or organizations that support career development, and Participating in a school sponsored internship when the scholarship is awarded.

Date Submitted: \_\_\_\_\_ PUID: \_\_\_\_\_

Last Name: \_\_\_\_\_ First Name: \_\_\_\_\_ Middle: \_\_\_\_\_

Permanent Address: \_\_\_\_\_ City: \_\_\_\_\_

State: \_\_\_\_\_ Zip Code: \_\_\_\_\_ Country: \_\_\_\_\_

Cell Phone: \_\_\_\_\_ E-mail: \_\_\_\_\_

Expected graduation date: \_\_\_\_\_ School year applying for: \_\_\_\_\_

Classification: Senior Junior Sophomore Freshman G.P.A. (Overall) \_\_\_\_\_Field of Interest: Lodging Foodservice Tourism Other \_\_\_\_\_

**(The following two questions are for our purposes only in awarding an HTM scholarship in a timely way so the scholarship recipient does not lose aid).**

1. Have you applied for financial aid through the Purdue Financial Aid office? Yes No
2. Are you currently receiving/anticipate receiving a Pell Grant? Yes No

**The applicant will include a one to two letter detailing to the committee why you are applying for this and reasons as to why you should receive this scholarship.**

**Return the completed application, resume and essay no later than September 14<sup>th</sup> to:**  
Maria Poynter at [poynterm@purdue.edu](mailto:poynterm@purdue.edu).

*For additional information or questions, contact: Dr. Hugo Tang [tang14@purdue.edu](mailto:tang14@purdue.edu)*

*If I am selected for a scholarship, award, or prize, I authorize Purdue University to release my name, major and hometown to the donor(s) and confirm that all criteria for selection were met. In addition, I agree to send a letter of appreciation to the donor and participate in events associated with any scholarship, award, or prize I may receive.*

***I certify that this information is true to the best of my knowledge.***

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

This application permits you to be considered for scholarships that the HTM Department awards for companies or associations. Information on additional scholarships you can apply for will be posted on the HTM webpage.